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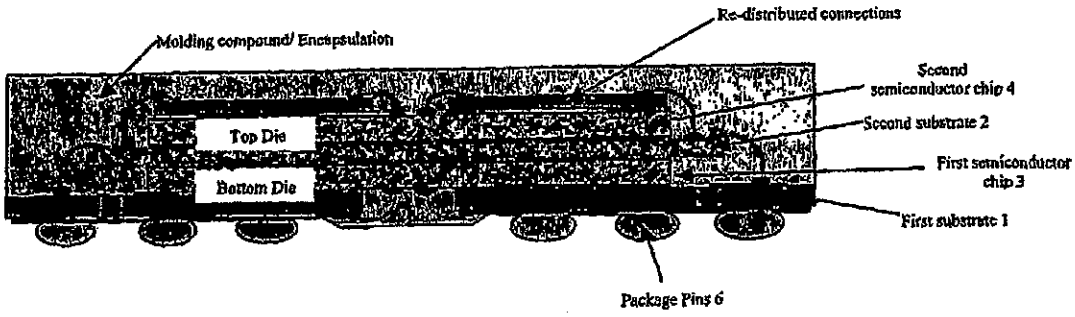
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(54) **Title:** MULTIPLE STACKED DIE WINDOW CSP PACKAGE AND METHOD OF MANUFACTURE



(57) **Abstract:** A semiconductor package including a first substrate having a die receiving area, a first adhesive layer, a window opening, and a plurality of conductive traces, a first semiconductor die having two sides and with an electrically active side mounted to the substrate through the first adheisve layer, a second adhesive layer having a first side attached to an electrically inactive side of the first semiconductor die, a second substrate having a die receiving area and a plurality of conductive traces and terminals, a last adhesive layer having a first side attached to a side of the second substrate with the terminals, a last semiconductor die having two sides and with an electrically inactive side being mounted to the second side of the third adhesive layer, and an electrically active side being electrically coupled to the conductive traces of the first or second substrate directly or through a redistribution device, and an encapsulant to encapsulate the semiconductor dies and electrical coupling, and signal transferring interconnects to transfer an electrical signal from the conductive traces to the exterior of the package.

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